

**Features:**

- n Isolated mounting base 3000V~
- n Pressure contact technology with Increased power cycling capability
- n Space and weight saving

Typical Applications

- n Various rectifiers
- n DC supply for PWM inverter

Part No. MDx1500-18-436F3

V _{RRM} , V _{DRM}	Type & Outline
1000V	MDx1500-10-436F3
1200V	MDx1500-12-436F3
1400V	MDx1500-14-436F3
1600V	MDx1500-16-436F3
1800V	MDx1500-18-436F3
1800V	MD1500-18-436F3G

MDx stands for any type of MDC, MDA, MDK

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _c =100°C	150			1500	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			130	mA
I _{FSM}	Surge forward current	V _R =60%V _{RRM} , t=10ms half sine	150			40	kA
I ² t	I ² t for fusing coordination					8000	10 ³ A ² s
V _{FO}	Threshold voltage		150			0.95	V
r _F	Forward slope resistance					0.10	mΩ
V _{FM}	Peak forward voltage	I _{FM} =3000A	25			1.50	V
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled per chip				0.025	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled per chip				0.018	°C/W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} : 1mA(MAX)		3000			V
F _m	Terminal connection torque(M14)				20		N·m
	Mounting torque(M12)				14		N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				6800		g
Outline	436F3						

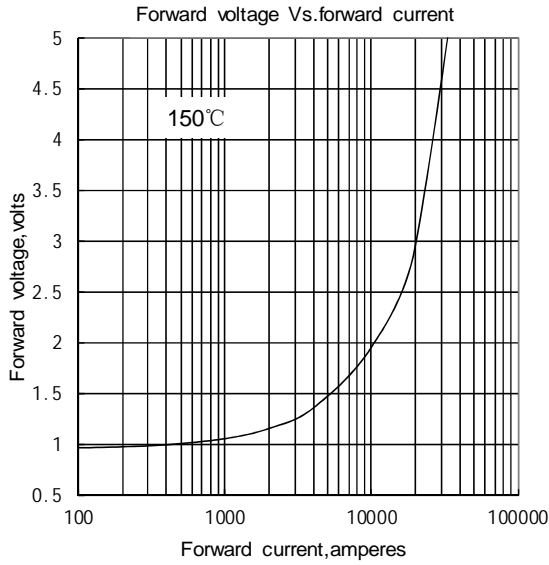


Fig.1

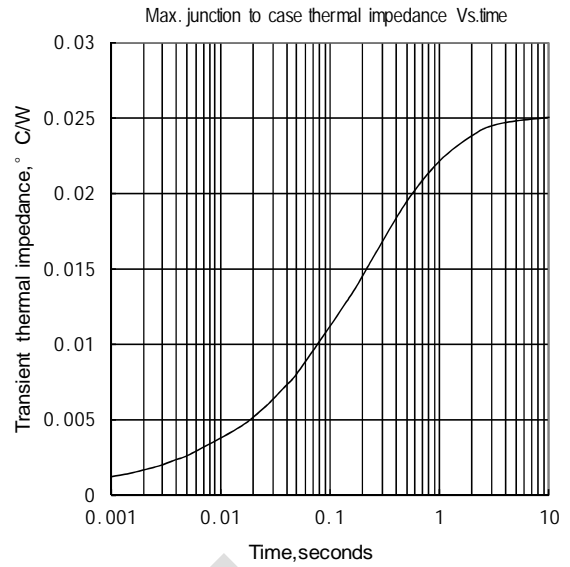


Fig.2

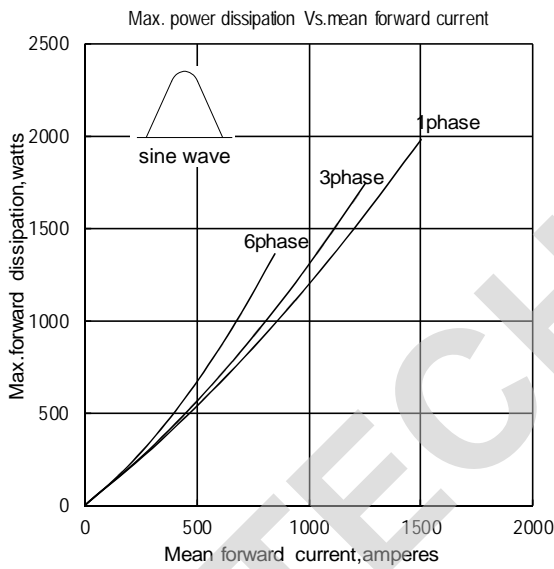


Fig.3

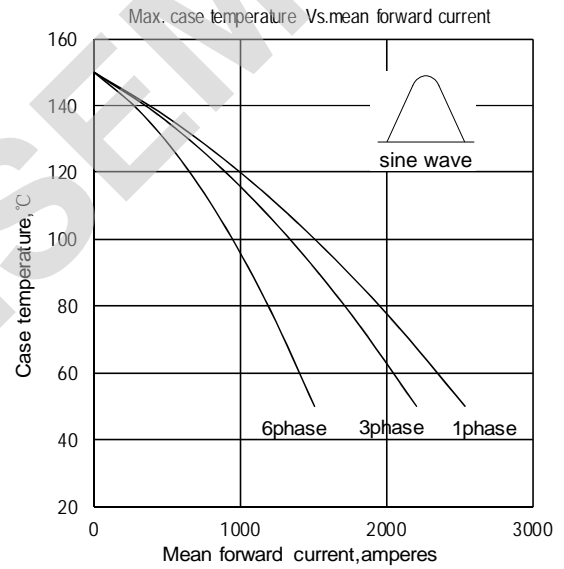


Fig.4

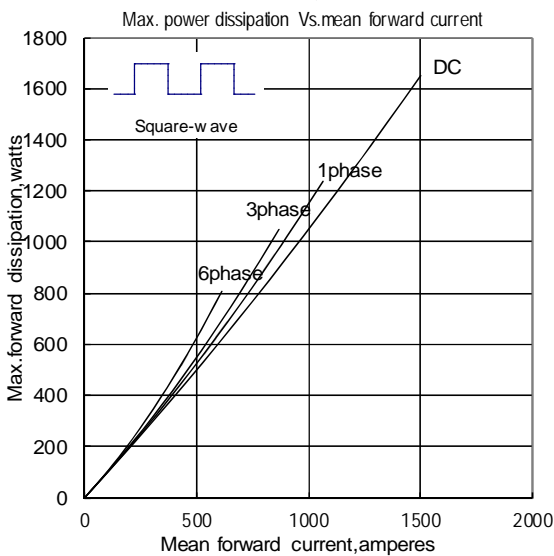


Fig.5

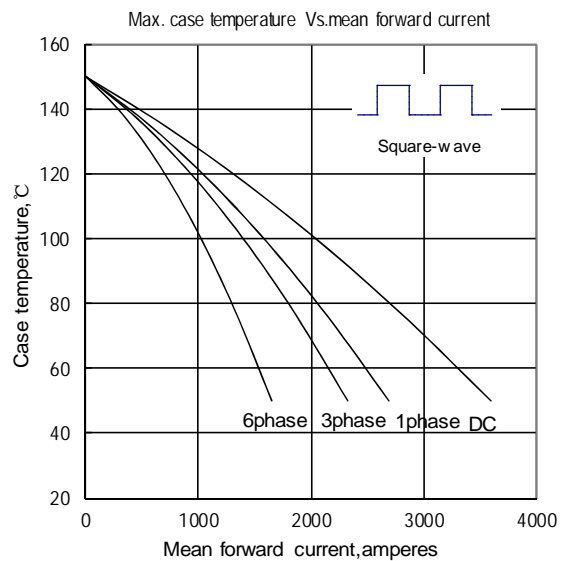


Fig.6

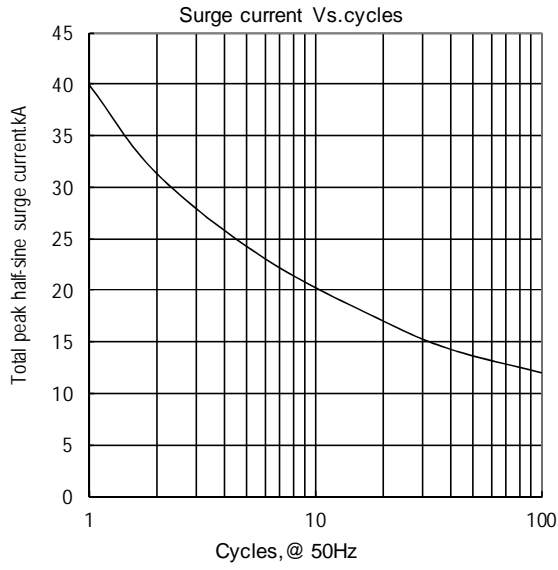


Fig.7

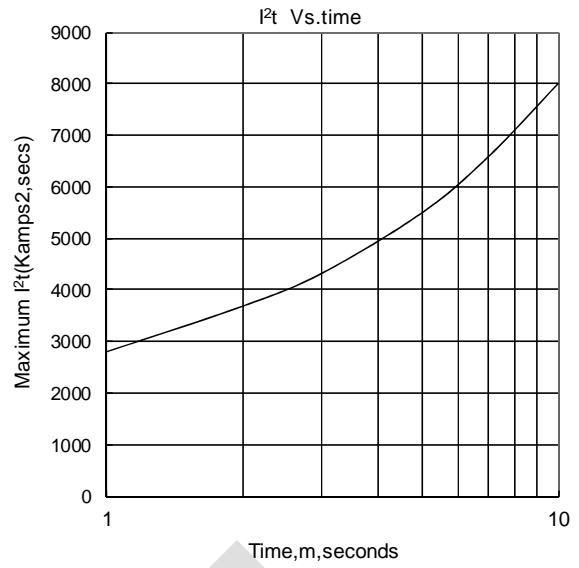
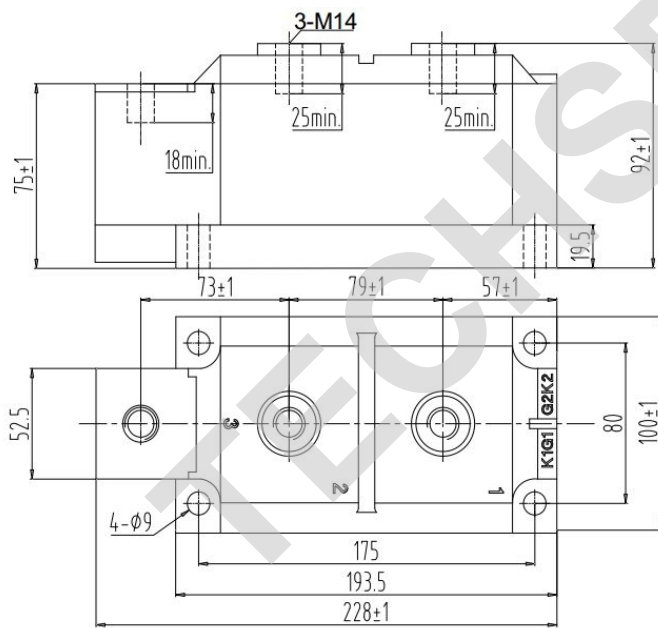


Fig.8

Outline:



Unmarked dimensional tolerance: ±0.5mm

